



PCNS Passive Components Networking Days Sep 12th - 15th 2017

Final Programme

Brno, Czech Republic

jointly organised by:



main sponsors:



Tuesday Sep 12th pre-event			
12:00 to 13:00	Registration Desk Opening		
13:00 to 17:00	CLR Seminars Capacitors Capacitor Technology Overview Ing. Tomáš Zedníček Ph.D. EPCI	Resistors Resistor Technology Overview Dipl.-Ing. Reiner W. Kühl Independent Specialist	Inductors Inductors for SMPS with high efficiency and best EMI Lorandt Fölkel M.Eng. Würth Elektronik
17:00 to 19:00	CEITEC Tour 17:00 move to CEITEC Central European Institute of Technology CEITEC Tour		

Wednesday Sep 13th			
8:00 to 9:00	Registration Desk Opening		
9:00 to 9:15	Opening Ceremony	Welcome Speech Tomáš Zedníček, European Passive Components Institute EPCI	
9:15 to 9:45	Keynote Speech	Plenary I. Independent Laboratory Feedback on All Industry Passive Components Failure Analysis Eric Zaia, Serma Technology	
9:45 to 10:15		Plenary II. Power-over-Coax Filter Design Challenges for Automotive Vision Applications Luděk Šubrt, Valeo	
10:15 to 10:45	Break		
10:45 to 13:00	Networking	Speakers Introduction 5 min flash introduction of speakers and invitation to their speech	
13:00 to 14:00	Lunch Break		
14:00 to 15:00	Networking	University and Industry Introduction 5 min flash presentations of universities and companies	
15:00 to 15:30	Break		
15:30 to 15:55	Speaker Session I. Space Components	1.1. Approach for passive parts procurement for space in New Space scenario David Nunez Teruel, Alter Technology	
15:55 to 16:20		1.2. Ta SMD capacitors with Polymer Counter Electrode for Space Applications Ana Tomás, Kemet	
16:20 to 16:45		1.3. Passive component embedding in printed circuit boards for space applications Maarten Cauwe, IMEC	
16:45 to 17:10		1.4. High reliable fuses versus COTS fuses Bruno Zemp, Schurter AG	
17:30 to 19:30	Welcome Drink	Networking and Welcome Drink at the Conference Venue Art of Sabrage	



Thursday Sep 14th		
8:00 to 9:00	Registration Desk Opening	
9:00 to 9:30	Session II.	2.1. Lessons learnt at ESA from failure with commercial product/proces in space applications Denis Lacombe and Léo Farhat, ESA
9:30 to 10:00	Hot Topic Panel Discussion	2.2. Parametric Failures in COTS Capacitors Alexander Teverovsky, ASRC Federal Space and Defense (NASA)
10:30 to 11:00	Commercial for Space Components	2.3. Commercial vs. Hi-Rel Tantalum Capacitors in Space Applications Yuri Freeman and Philip Lessner, Kemet
11:00 to 11:30		Panel Discussion Q&A from audience
11:30 to 11:45	Break	
11:45 to 12:05	Speaker Session III.	3.1. Assessment of Supercapacitor's Quality by Means of Low Frequency Noise Arkadiusz Szewczyk, Gdańsk University of Technology Invited Paper
12:05 to 12:30		3.2. Investigation of Supercapacitor's Impedance Based on Spectroscopic Measurements Ciprian Ionescu, University Politehnica of Bucharest CETTI
12:30 to 12:55	Super-capacitors	3.3. Supercapacitor Degradation and Reliability Tomáš Kuparowitz, Central European Institute of Technology CEITEC Brno
12:55 to 14:00	Lunch Break	
14:00 to 14:25	Speaker Session IV. Part 1	4.1. Aerosol Jet® Printing Opportunity Jiří Navrátil, FEE University of West Bohemia RICE Invited Paper
14:25 to 14:50		4.2. Next Generation of Polymer Capacitors: Boosting Performance of Electrolytic Capacitors by Conductive Polymer Dispersions Udo Merker, Heraeus Deutschland GmbH & Co KG
14:50 to 15:15	New Development	4.3. Printed and Embroidered Electronic Passive Components Tomáš Blecha, FEE University of West Bohemia
15:15 to 15:45	Break	
15:45 to 16:10	Speaker Session IV. Part 2	4.4. Embroidered textile antennas based on hybrid sewing thread Martin Pavec, FEE University of West Bohemia RICE
16:10 to 16:35	New Development	4.5. Carbon nanotubes ammonia sensor printed by Aerosol Jet System Jiří Štulík and Aleš Hamáček, FEE University of West Bohemia
17:00 to 24:00	Gala Dinner	Networking and Gala Dinner at Templar Knights Wine Cellar Cejkovice coach transport leaves 17:00 from the venue and back at the scheduled times



Friday Sep 15th		
8:00 to 9:00	Registration Desk Opening	
9:00 to 9:25	Speaker Session V. Applications	5.1. Use of passive parts at extended temperature range David Nunez Teruel and Demetrio López Molina, Alter Technology Invited Paper
9:25 to 9:50		5.2. Energy harvesting is not fiction any more Lorandt Fölkel, Würth Elektronik eiSos GmbH & Co.KG
9:50 to 10:15		5.3. Tantalum Polymer Capacitors: Hermetic Packaging Solutions for Space Applications Chris Reynolds, AVX Corporation
10:15 to 10:45		5.4. Project Towards Energy Storage on a Chip Jaromír Hubálek, Central European Institute of Technology CEITEC Brno
10:45 to 11:00	Break, Sandwiches to Go	
11:00 to 11:25	Speaker Session VI. Quality & Processes	6.1. Moisture-Related Reverse Bias Degradation in Chip Tantalum Capacitors and Kinetics of Moisture Sorption Alexander Teverovsky, ASRC Federal Space and Defense (NASA)
11:25 to 11:50		6.2. Temperature Dependence of Leakage Current Degradation of Tantalum Capacitors at High Electric Field Vlasta Sedláková, Brno University of Technology, CEITECet
11:50 to 12:15		6.3. Thick Film Power Resistor with Thick Printed Copper Terminals Jiří Hlína, FEE University of West Bohemia RICE
12:15 to 12:40		6.4. Electron Transport and Noise of the Chip PTC Thermistors Zdeněk Šita, TDK EPCOS s.r.o. Šumperk
12:40 to 13:00	Closing Ceremony	Closing Speech Tomáš Zedníček, EPCI